

AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) An electrical ~~multilayer~~ component having multiple layers (1), the electrical [[-]] comprising at least one of a capacitor, a temperature-dependent resistor, and a varistor, said multilayer component comprising:

[[-]] a main body (5) constructed from stacked dielectric layers that are stacked to form a main body; [[,]]

[[-]] multiple electrode areas electrodes positioned in the main body at intervals between at least some of the dielectric material layers; [[,]] in which areas electrodes (10A, 15A) are formed,

[[-]] at least two bumps (10, 15) for the configured to act as electrical contacts for contact of the electrical component, which the bumps are positioned being on the a surface of the main body; and (5),

[[-]] the bumps (10, 15) being electrically connected to at least one of said electrodes (10A, 15A) via through contacts (6) arranged in the main body[[,]] that electrically connect bumps and electrodes;

wherein the electrodes comprise first and second electrode stacks, so that a first and a second electrode stack (10B, 15B) are formed, wherein each of said first and second

~~stack contacts only the first and second electrode stacks contacting one of said the bumps (10,15).~~

2. (Currently Amended) The electrical multilayer component according to of claim 1, [[-]] wherein a first contact electrically connects electrodes in the first electrode stack to a bump, and a second contact electrically connects electrodes in the second electrode stack to a bump a plurality of electrodes (10A) is provided in same electrode stack (10B), said electrodes being arranged in different electrode areas, [[-]] said electrodes (10A) being connected to one another in an electrically conductive way using said through contacts (6).

3. (Currently Amended) The electrical multilayer component of claim 1 (1) according to one of the preceding claims, [[-]] wherein said the first and second electrode stacks (10B, 15B) face one another each other in the main body; and (5), [[-]] wherein the main body comprises a an electrode free region (11) of the main body (5) is provided between the two first and second electrode stacks that does not contain an electrode.

4. (Currently Amended) The electrical multilayer component of claim 1 according to one of claims 1 or 2, [[-]] wherein the electrodes (10A, 15A) of from the first and second stack electrode stacks overlap one another.

5. (Currently Amended) The electrical multilayer component of claim 1 (1) according to one of the preceding claims, [[-]] wherein further comprising:
floating electrodes (60) are provided in the main body (5), wherein said the floating electrodes do not contact any of the bumps (10, 15).

6. (Currently Amended) The electrical multilayer component of claim 5 according to the preceding claim, [[-]] wherein the floating electrodes (60) overlap with the electrodes (10A, 15A) of from at least one of the first (10B) and the second electrode stacks (15B).

7. (Currently Amended) The electrical multilayer component of claim 1 (1) according to one of the preceding claims, [[-]] further comprising:
wherein a third bump (20) is provided on the a surface of the main body; and[[,]]
[[-]] wherein at least one a third electrode stack (20B) is provided in the main body (5), said the third electrode stack comprising at least one electrode (20A), wherein said the third electrode stack is connected in an electrically conductive way to being electrically connected to the third bump (20) via a contact; through contacts (6),

[[-]] wherein the at least one electrode (20A) of in the third electrode stack (20B) overlapping overlaps with an electrode (10A, 15A) of in at least one of the first (10B) and the second electrode stacks (15B).

8. (Currently Amended) The electrical multilayer component according to of claim 7, [[-]] wherein the electrodes (10A, 15A) of in the first (10B) and the second electrode stacks (15B) do not overlap one another.

9. (Currently Amended) The electrical multilayer component of claim 7 according to one of preceding claims 7 or 8, [-]] wherein the first (10B), second (15B), and third electrode stacks (20B) each comprise one electrode (10A, 15A, 20A).

10. (Currently Amended) The electrical multilayer component of claim 7 according to one of claims 7 through 9, [-]] wherein the overlap areas (21, 22) between the electrodes of different pairs of from different electrode stacks (10B, 15B, 20B) have different sizes with respect to one another.

11. (Currently Amended) The electrical multilayer component of claim 7 according to the preceding claim, [-]] wherein the electrode overlap areas (21, 22) between the third electrode stack (20B) and the first electrode stacks (10B) have different sizes with respect to the than electrode overlap areas (21, 22) between the third electrode stack (20B) and the second electrode stack (15B).

12. (Currently Amended) The electrical multilayer component of claim 7 according to one of claims 7 through 11, further comprising:

[[-]] wherein a fourth bump on a surface of the main body; (25) and fifth bump (30) are provided on the surface of the main body (5),
a fifth bump on a surface of the main body;
[[-]] wherein a fourth (25B) and a fifth electrode stack (30B) comprising electrodes in the main body; (25A, 30A) are provided,
a fifth electrode stack comprising electrodes in the main body; and
[[-]] wherein contacts that contact the forth fourth electrode stack (25B) is connected to the fourth bump (25) via through contacts (6), and wherein and that contact the fifth electrode stack (30B) is connected to the fifth bump; (30) via through contacts (6),
[[-]] wherein the electrodes (25A) of in the fourth electrode stack (25B) overlapping with the overlap electrodes (15A) of in the second electrode stack (15B) and the electrodes (30A) of in the fifth electrode stack (30B).

13. (Currently Amended) The electrical multilayer component of claim 1 according to one of the preceding claims, further comprising:

[[- wherein further]] additional bumps are provided on the surface of the main body; and [[,]]
[[- wherein further]] additional electrode stacks are provided in the main body, said further each of the additional electrode stacks being each connected to a corresponding additional respective further bump.

14. (Currently Amended) The electrical multilayer component according to of claim 13, [[-]] wherein at least some ~~of the~~ electrodes (20A, 80A) ~~of~~ from different electrode stacks (20B, 80B) are electrically connected to one another ~~in an electrically conductive way.~~

15. (Currently Amended) The electrical multilayer component of claim 12 according to ~~one of the preceding claims~~, [[-]] wherein all bumps are ~~positioned on the on~~ a same main surface of the main body.

16. (Currently Amended) The electrical multilayer component of claim 1 according to ~~one of the preceding claims~~, [[-]] wherein the dielectric layers comprise a ceramic material.

17. (Currently Amended) The electrical multilayer component according to of claim 16, [[-]] wherein the ceramic material comprises a varistor ceramic based on one of ZnO-Bi and ZnO-Pr.

18. (Currently Amended) The electrical multilayer component according to of claim 16, [[-]] wherein the ceramic material comprises a capacitor ~~ceramics which~~ ceramic comprising is one of NPO ceramics and doped BaTiO₃.

19. (Currently Amended) The electrical multilayer component according to of claim 16, [[-]] wherein the ceramic material comprises at least one of nickel, manganese, spinel, and perovskite.

20. (Currently Amended) The electrical multilayer component of claim 1 according to one of the preceding claims, [[-]] wherein the dielectric layers comprise glass.

21. (Currently Amended) The electrical multilayer component of claim 1 according to one of the preceding claims, further comprising:
at least three additional bumps on the [[-]] wherein at least five bumps are provided
on same main surface of the main body; and [[,]]
at least three additional [[-]] wherein at least 5 electrode stacks are provided in the
main body, said stacks being connected to a respective each of the electrode stacks being
electrically connected to a corresponding bump;[[,]]
[[-]] wherein the main body has an area which is smaller of less than 2.5 mm².

22. (Currently Amended) The electrical multilayer component of claim 1 according to one of claims 1 through 20, further comprising:

at least seven additional [[-]] wherein at least nine bumps are provided on same
main the surface of the main body; and [[,]]

at least seven additional [[-]] wherein at least 9 electrode stacks are provided in the main body, said each of the electrode stacks being electrically connected to a corresponding respective bump: [[,]]

[[-]] wherein the main body has an area which is smaller of less than 5.12 mm².

23. (Currently Amended) The electrical multilayer component of claim 1 according to one of claims 1 through 20, further comprising:

at least nine additional [[-]] wherein at least eleven bumps are provided on same main the surface of the main body; and [[,]]

at least nine additional [[-]] wherein at least 11 electrode stacks are provided in the main body, said stacks each electrode stack being electrically connected to a respective corresponding bump: [[,]]

[[-]] wherein the main body has an area which is smaller of less than 8 mm².

24. (Currently Amended) The electrical multilayer component of claim 1 according to one of the preceding claims, [[-]] wherein the through contacts (6A, 6B) are provided in the form of comprise channels in the main body, in which channels that contain an electrically conductive material is arranged.

25. (Currently Amended) The electrical multilayer component according to of claim 24, [[-]] wherein the through holes channels have one of a round and a rectangular cross-section.

26. (Currently Amended) The electrical multilayer component of claim 1
according to one of claims 24 or 25, further comprising:

additional contacts in the main body [[-]] wherein the that electrically interconnect
connect electrodes of a respective in a single electrode stack are connected to one another
in an electrically conductive way by a plurality of through contacts, said through the
additional contacts being arranged in different dielectric layers and being offset to from
one another, the electrical component comprising first additional contacts for the first
electrode stack and second additional contacts for the second electrode stack.

27. (Currently Amended) The electrical multilayer component according to of
claim 26, [[-]] wherein the main body has two opposite main surfaces (300, 400) and two
front faces (500, 600), the bumps (10, 15) being positioned on the main surfaces; and (300,
400),

[[-]] wherein through contacts (6A) arranged closest closer to the bumps (10, 15)
have are at a greater distance to from neighboring front faces (500, 600) of the electrical
component than the through contacts (6B) arranged further farther away from the bumps
(10, 15).

28. (Currently Amended) The electrical multilayer component according to of
claim 24, [[-]] wherein the electrically conductive material comprises at least one of Ag,
AgPd, AgPt, AgPdPt, Pd, Pt, and Cu.

29. (Currently Amended) An arrangement containing a comprising:
the electrical multilayer component of claim 1; and (1) according to one of the
preceding claims,

[-]] comprising a carrier substrate (100) and comprising contact pads (90) for
contacting connecting to the electrical component, said the contact pads being arranged on
the a surface of said the carrier substrate;[[,]]

[- the multilayer]] wherein the electrical component being is mounted on the
carrier substrate (100) in a flip chip arrangement with clearance relative to said the carrier
substrate; and[[,]]

[- said multilayer]] wherein the electrical component is electrically connected to
being connected to said carrier substrate in an electrically conductive way via the contact
pads (90) by means of said via the bumps (10, 15, 20).

30. (Currently Amended) A method for manufacturing a multilayer an electrical
component comprised of multiple layers, said method the method comprising the
following steps:

[[A]] forming a main body (5) having comprising dielectric layers, electrodes,
(10A, 15A) and through contacts (6A, 6B) arranged in the an interior of said the main
body, is produced in that a layer stack is provided of the electrodes being (10A, 15A)
positioned between at least some of the dielectric layers, said the dielectric layers having

through holes[[],] that contain an electrically conductive material that forms the contacts,
and being provided in the through holes,

[[B]] forming bumps (10, 15) are produced directly on the ~~respective~~ through
contacts.

31. (Currently Amended) The method according to of claim 30, [[-]] wherein ~~in~~
~~step A)~~ a the main body having has two main surfaces (300, 400) and at least two front
faces (500, 600) is produced, the through contacts comprising (6A, 6B) being produced in
~~the form of~~ channels in the interior of the main body (5) running that run transversely to
the main surfaces; and [[,]]

[[-]] wherein ~~in step B)~~ the bumps are produced formed on the main surfaces.

32. (Currently Amended) The method of claim 30 according to one of claims 30
~~or 31, [[-]] wherein~~ ~~in~~ ~~step A)~~ the through contacts (6A, 6B) are produced formed in
different dielectric material layers[[, through]] such that contacts (6A, 6B) in neighboring
dielectric layers being produced are offset relative to each other one another.

33. (Currently Amended) The method of claim 30 according to one of claims 30
~~through 32, [[-]] wherein~~ ~~in~~ ~~step A)~~ the through contacts (6A) which that are closest closer
to the bumps (10, 15) have are at a greater distance to from neighboring front faces (500,
600) than through contacts (6B) which that are further farther from the bumps (10, 15).